

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> Sat, May 19, 2012 02:32 AM
<b>Contact Name *</b> David Lancaster	Title - Contact Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	Title - Representative Product Ecology	<b>Phone - Representative *</b> 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FAN21SV04EMPX	FAN21SV04EMPX	25-MLP 5X6 (BW Au&Cu) (G)			INTERNAL PENANG	0.069	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	1	260 C	30 seconds	3

\* Required Field

<b>RoHS Material Composition Declaration</b>	<b>Declaration Type * Custom</b>
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<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

<b>RoHS Declaration *</b>	<b>1 - Item(s) does not contain RoHS restricted substances per the definition above</b>	<b>Supplier Acceptance * Accepted</b>
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**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC  
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<b>Declaration Signature</b>
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Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name 25-MLP 5X6 (BWAu&Cu) (G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	2.740	Supplier		Silicon	2.740	7440-21-3	39826
Die Attach	Other Organic Materials	0.518			Resin	0.026	54208-63-8	376
					Silver	0.492	7440-22-4	7151
Encapsulation	Thermoplastics	40.900			Carbon Black	0.409	1333-86-4	5945
					Epoxy Resin	8.180	29690-82-2	118895
					Silica	32.311	60676-86-0	469637
Lead Frame	Other Ferrous alloys, non-stainless steels	23.905			Copper	23.200	7440-50-8	337209
					Iron	0.621	7439-89-6	9026
					Phosphorus	0.036	7723-14-0	522
					Zinc	0.048	7440-66-6	695
Terminal Finish	Precious metals	0.233			Gold	0.003	7440-57-5	51
					Nickel	0.209	7440-02-0	3031
					Palladium	0.021	7440-05-3	305
Wire Bond Au	Precious metals	0.296			Gold	0.296	7440-57-5	4302
Wire Bond Cu	Copper & its alloys	0.253			Copper	0.253	7440-50-8	3677